# JK-SMD0603-025 PPTC DEVICES

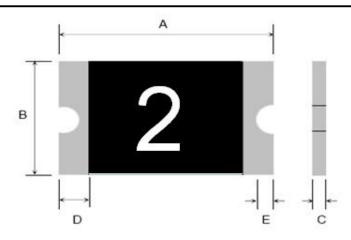
Part Number: Q/JKTD-6-025





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Terminal pad materials: Tin-Plated Nickle-copper

Terminal pad solderability: Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.

Marking: Part identification 3=025

Table1:DIMENTION(Unit:mm)

Model	Marking	A		В		С		D	E
Model		Min.	Max.	Min.	Max.	Min.	Max	Min.	Max.
JK-SMD0603-025	2	1.45	1.85	0.65	1.05	0.40	1.00	0.15	0.40

## Table2:PERFORMANCE RATINGS:

Model	Markina	$V_{\text{max}}$	I <sub>max</sub>	I <sub>hold</sub>	I <sub>trip</sub>	P <sub>d</sub>	Maxin Time To		Resis	stance
Model	Marking	(Vdc)	(A)	@25°C	(A)	Typ (W)	Current	Time	Rimin	R1 <sub>max</sub>
				(A)	(A)	(**)	(A)	(Sec)	$(\Omega)$	$(\Omega)$
JK-SMD0603-025	2	6.0	40	0.25	0.55	0.50	8.0	0.08	0.500	3.000

### Table3:Test Conditons and Standards

Item	Test Conditon	Standard		
Initial Resistance	25℃	$0.500{\sim}3.000\Omega$		
$I_{H}$	25℃, 0.25A, 60min	No Trip		
Ttrip	25℃, 8A	≤0.08S		
Trip endurance	6V, 40A, 60min	No arcing or burning		

Operating Temperature: -40°C TO 85°C

Packaging: Bulk,5000pcs per bag

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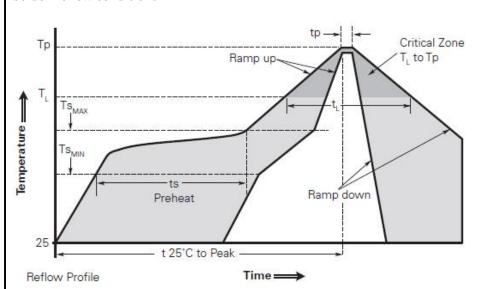


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#### **Solder reflow conditions**



Profile Feature	Pb-Free Assembly
Average ramp up rate (Ts <sub>MAX</sub> to Tp)	3°C/second max.
Preheat	100
<ul> <li>Temperature min. (Ts<sub>MIN</sub>)</li> </ul>	150°C
<ul> <li>Temperature max. (Ts<sub>MAX</sub>)</li> </ul>	200°C
<ul> <li>Time (ts<sub>MIN</sub> to ts<sub>MAX</sub>)</li> </ul>	60-120 seconds
Time maintained above:	
• Temperature (T <sub>L</sub> )	217°C
• Time (t <sub>L</sub> )	60-150 seconds
Peak/Classification temperature (Tp)	260°C
Time within 5°C of actual peak temperat	ure
Time (tp)	30 seconds max.
Ramp down rate	3°C/second max.
Time 25°C to peak temperature	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temprature profile meets RoHs leadfree process.

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

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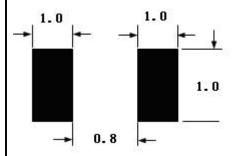




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### Recommended pad layout (mm)



### WARNING

- · Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- · PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- · Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- · Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- · Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- · Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.PPTC SMD can be cleaned by standard methods.
- · Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profilecould negatively impact solderability performance of our devices.

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